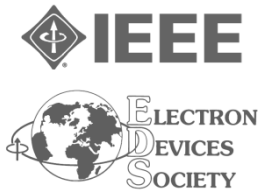




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International Conference on Simulation of Semiconductor Processes and Devices (SISPAD) 2016

Second Call for Papers

The 21st SISPAD will be held from September 6 to 8, 2016, in Nuremberg, Germany.

Following the 20 years tradition of the SISPAD conference series as the leading forum for Technology Computer-Aided Design (TCAD), the conference provides an opportunity for the presentation and discussion of recent advances in modeling and simulation of semiconductor devices, processes and equipment. The scientific program consists of invited and contributed presentations and a poster session. Companion workshops are planned for September 5.

General Topics

- Process simulation and modeling
- Equipment simulation
- Material modeling
- Electronic transport in semiconductor materials and devices
- Device simulation
- Interconnect modeling and algorithms
- Models of VLSI device scaling limits
- Compact modeling for circuit simulation
- Integration of process, device and circuit simulation
- Simulation of variability
- Advanced numerical methods and algorithms
- Fundamental aspects of device modeling and simulation
- Benchmarking, calibration and verification of simulators

Abstracts and Proceedings

A two-page abstract (A4, 10 – 12 pt, pdf) should be sent to info@sispad2016.org. Authors of accepted papers are requested to submit a four-page final paper which will be published in the conference proceedings.

Important Dates

Abstract submission deadline	April 15, 2016
Notification of acceptance	June 6, 2016
Final paper	July 4, 2016
Conference	September 6-8, 2016

Venue

The conference will be held at the international conference hotel "Le Méridien Grand Hotel Nuremberg" which is located opposite the main train station.

Further information and contact:

www.sispad2016.org
info@sispad2016.org